

**TOSHIBA CORPORATION**

Semiconductor & Storage Products Company  
Oita Operations

3500, Matsuoka Oita City OITA 870-0197, JAPAN  
PHONE: +81-97-524-6091  
FACSIMILE: +81-97-524-6287

Date: January 29, 2016

Ref. No.: 0-HKN-15- 00097E

To: Digi Key Corporation

Dear Sir/ Madam:

**Change in Outer Box for SPP25 pin Products**

We greatly appreciate your continued business.

This is to notify our customers of our plan to change method of dry packing for our products supplied to you.  
Full details of the planned change are given in the following page.

If you have any questions or inquiry regarding this change, please inform our Sales representatives nearest you as soon as possible.

We appreciate your understanding and cooperation.

Yours faithfully,

Prepared by H. Kashima

Approved by:



M. Kameno, Manager

Quality & Reliability Group

Quality Assurance Dept.

Oita Operations

Semiconductor & Storage Products Company

TOSHIBA Corporation

**Change in Outer Box for SPP25 pin Products**

1. Product to be Affected : **TB2941HQ(O)**  
**TB6549HQ(O)**  
**TB67S142HG(O)**  
**TB67S149HG(O)**
2. Description of Change : - Change in dimensions of outer box  
-Change in packing form of inner box in outer box  
-Change in the number of buffer materials per outer box
3. Reason of Change : To perform uniform management and provide stable supply by integrated production
4. Scheduled Date of Change : The new method is scheduled to be applied to lots produced in February, 2016 and afterward.
5. Remark : If you have any questions or requests regarding this change, please inform our Sales representatives nearest you as soon as possible.

# Change in Outer Box for SPP25 pin Products

Date: January 29, 2016  
TOSHIBA Corporation  
Semiconductor & Storage Products Company  
OITA Operations  
Quality Assurance Dept.

[1] **Target product**

See List of affected products

[2] **Reason of Change**

To perform uniform management and provide stable supply by integrated production

[3] **Description of Change**

Change in dimensions of outer box

Change in packing form of inner box in outer box

Change in the number of buffer materials per outer box


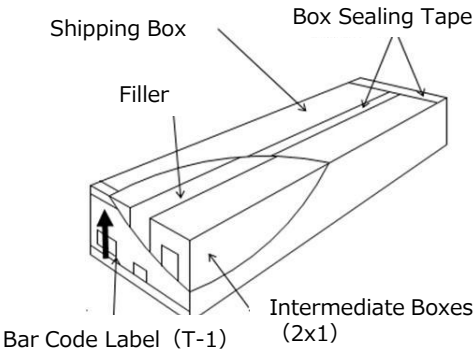

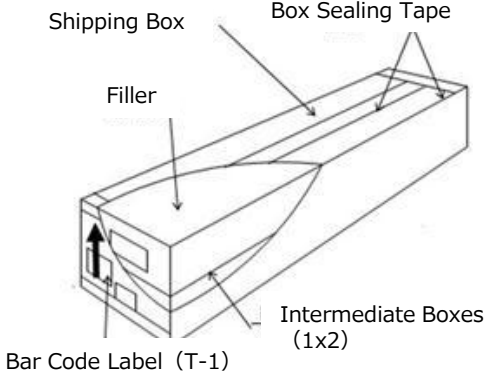
[4] **Changeover schedule**

The new method is scheduled to be applied to lots produced in

February 2016 and afterward.

**Your consideration and approval for this change will be highly appreciated.**

# Comparison between Current and New Outer Box

	Current outer box	New outer box
Package type (power IC)	SPP25pin (HZIP25P-1.00F)	
Location of packing	Oita factory	
Outer box code	8 B A 6 6 1 P1	8 B A 6 6 1 R 1
Dimension of outer box	(Inner dimension L:635mm x W:260mm x H:185mm)	(Inner dimension L:620mm x W:175mm x H:180mm)
Number of inner boxes	2 inner boxes per outer box	2 inner boxes per outer box
Packed appearance of inner boxes in outer box	 	 
Number of buffer materials (Number used)	14pcs per outer box	0pc per outer box

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**TOSHIBA**  
**Leading Innovation >>>**